



Single channel high side driver for automotive applications

Features

Max supply voltage	V _{CC}	41V
Operating voltage range	V _{CC}	4.5 to 28V
Max on-state resistance (per ch.)	R _{ON}	50 mΩ
Current limitation (typ)	I _{LIMH}	27A
Off state supply current	I _S	2 μA ⁽¹⁾

1. Typical value with all loads connected.

General

- Inrush current active management by power limitation
- Very low stand-by current
- 3.0V CMOS compatible inputs
- Optimized electromagnetic emissions
- Very low electromagnetic susceptibility
- In compliance with the 2002/95/EC european directive

Diagnostic functions

- Open Drain status output
- On-state open load detection
- Off-state open load detection
- Output short to V_{CC} detection
- Overload and short to ground (power limitation) indication
- Thermal shutdown indication

Protections

- Undervoltage shutdown
- Overvoltage clamp
- Load current limitation
- Self-limiting of fast thermal transients
- Protection against loss of ground and loss of V_{CC}
- Over-temperature shutdown with autorestart (thermal shutdown)
- Reverse battery protected (a)
- Electrostatic discharge protection



Application

All types of resistive, inductive and capacitive loads.

Description

The VN5E050J-E is a single channel high-side driver manufactured in the ST proprietary VIPower M0-5 technology and housed in the tiny PowerSSO-12 package.

The VN5E050J-E is designed to drive automotive grounded loads delivering protection, diagnostics and easy 3V and 5V CMOS-compatible interface with any microcontroller.

The device integrates advanced protective functions such as load current limitation, inrush and overload active management by power limitation, over-temperature shut-off with autorestart and over-voltage active clamp.

A dedicated active low digital status pin is associated with every output channel in order to provide Enhanced diagnostic functions including fast detection of overload and short-circuit to ground, over-temperature indication, short-circuit to V_{CC} diagnosis and ON & OFF state open-load detection.

The diagnostic feedback of the whole device can be disabled by pulling the STAT_DIS pin up, thus allowing wired-ORing with other similar devices.

a. See Application schematic.

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1 Block diagram and pin configuration

Figure 1. Block diagram

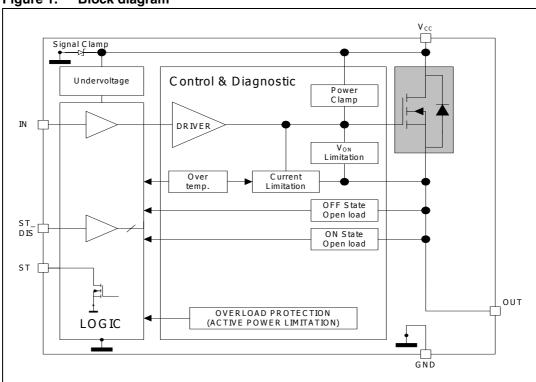


Table 1. Pin function

Name	Function
V _{CC}	Battery connection.
OUTPUT	Power output.
GND	Ground connection. Must be reverse battery protected by an external diode/resistor network.
INPUT	Voltage controlled input pin with hysteresis, CMOS compatible. Controls output switch state.
STATUS	Open Drain digital diagnostic pin.
STAT_DIS	Active high CMOS compatible pin, to disable the STATUS pin.

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Figure 2. Configuration diagram (top view)

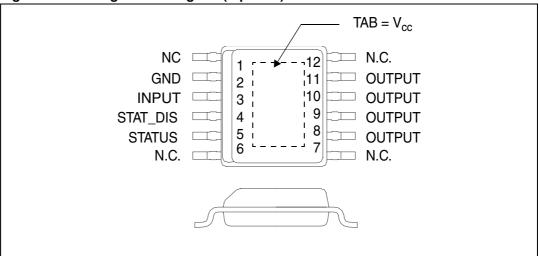
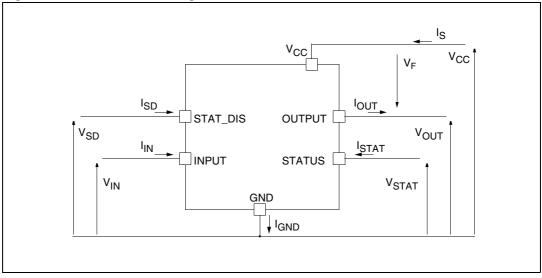


Table 2. Suggested connections for unused and not connected pins

Connection / pin	Status	N.C.	Output	Input	STAT_DIS
Floating	Х	Х	Х	Х	Х
To ground	Not allowed	Х	Not allowed	Through 10KΩ resistor	Through 10KΩ resistor

2 Electrical specifications

Figure 3. Current and voltage conventions



Note: $V_F = V_{OUT} - V_{CC}$ during reverse battery condition.

2.1 Absolute maximum ratings

Stressing the device above the ratings listed in the "Absolute maximum ratings" tables may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to the conditions in the "Absolute maximum ratings" tables for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CC}	DC supply voltage	41	V
-V _{CC}	Reverse DC supply voltage	0.3	V
-I _{GND}	DC reverse ground pin current	200	mA
I _{OUT}	DC output current	Internally limited	Α
-I _{OUT}	Reverse DC output current	15	Α
I _{IN}	DC input current	+10 / -1	mA
I _{STAT}	DC status current	+10 / -1	mA
I _{STAT_DIS}	DC status disable current	+10 / -1	mA
E _{MAX}	Maximum switching energy (L=3mH; R_L =0 Ω ; V_{bat} =13.5V; T_{jstart} =150°C; I_{OUT} = I_{limL} (<i>Typ.</i>))	104	mJ

Table 3. Absolute maximum ratings (continued)

Symbol	Parameter	Value	Unit
	Electrostatic discharge (Human Body Model: R=1.5KΩ; C=100pF)		
	- INPUT	4000	V
V_{ESD}	- STATUS	4000	V
	- STAT_DIS	4000	V
	- OUTPUT	5000	V
	- V _{CC}	5000	V
V _{ESD}	Charge device model (CDM-AEC-Q100-011)	750	V
T _j	Junction operating temperature	-40 to 150	°C
T _{stg}	Storage temperature	- 55 to 150	°C

2.2 Thermal data

Table 4. Thermal data

Symbol	I Parameter Value		Unit
R _{thj-case}	Thermal resistance junction-case (max) (with one channel ON)	2.7	°C/W
R _{thj-amb}	Thermal resistance junction-ambient (max)	See Figure 36	°C/W

2.3 Electrical characteristics

Values specified in this section are for 8V<V $_{CC}$ <28V; -40°C< Tj <150°C, unless otherwise stated.

Table 5. Power section

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{CC}	Operating supply voltage		4.5	13	28	V
V _{USD}	Undervoltage shutdown			3.5	4.5	V
V _{USDhyst}	Undervoltage shutdown hysteresis			0.5		٧
R _{ON}	On state resistance	I _{OUT} =2A; T _j =25°C I _{OUT} =2A; T _j =150°C I _{OUT} =2A; V _{CC} =5V; T _j =25°C			50 100 65	$m\Omega$ $m\Omega$ $m\Omega$
V _{clamp}	Clamp voltage	I _S = 20 mA	41	46	52	V
I _S	Supply current			2 ⁽¹⁾ 3	5 ⁽¹⁾ 6	μA mA
I _{L(off1)}	Off state output current	$V_{IN}=V_{OUT}=0V; V_{CC}=13V; \\ T_{j}=25^{\circ}C \\ V_{IN}=V_{OUT}=0V; V_{CC}=13V; \\ T_{j}=125^{\circ}C$	0	0.01	3 5	μ Α μ Α
V _F	Output - V _{CC} diode voltage	-I _{OUT} =2A; T _j =150°C			0.7	V

^{1.} PowerMOS leakage included.

Table 6. Switching ($V_{CC} = 13V$; $T_j = 25^{\circ}C$)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-On delay time	R_L =6.5 Ω (see <i>Figure 6.</i>)		20		μs
t _{d(off)}	Turn-Off delay time	R_L =6.5 Ω (see <i>Figure 6</i> .)		40		μs
dV _{OUT} /dt _(on)	Turn-On voltage slope	R _L =6.5Ω		See Figure 26.		V/µs
dV _{OUT} /dt _(off)	Turn-Off voltage slope	R _L =6.5Ω		See Figure 28.		V/µs
W _{ON}	Switching energy losses during twon	$R_L=6.5\Omega$ (see <i>Figure 6</i> .)		0.21		mJ
W _{OFF}	Switching energy losses during twoff	$R_L=6.5\Omega$ (see <i>Figure 6.</i>)		0.28		mJ

Table 7. Status pin (V_{SD}=0V)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{STAT}	Status low output voltage	I _{STAT} = 1.6 mA, V _{SD} =0V			0.5	V
I _{LSTAT}	Status leakage current	Normal operation or V_{SD} =5V, V_{STAT} = 5V			10	μΑ
C _{STAT}	Status pin input capacitance	Normal operation or V_{SD} =5V, V_{STAT} = 5V			100	pF
V _{SCL}	Status clamp voltage	I _{STAT} = 1mA I _{STAT} = - 1mA	5.5	-0.7	7	V V

Table 8. Protections (1)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{limH}	DC short circuit current	V _{CC} =13V; 5V <v<sub>CC<28V</v<sub>	19	27	38 38	A A
I _{limL}	Short circuit current during thermal cycling	V _{CC} =13V; T _R <t<sub>j<t<sub>TSD</t<sub></t<sub>		7		Α
T _{TSD}	Shutdown temperature		150	175	200	°C
T _R	Reset temperature		T _{RS} + 1	T _{RS} + 5		°C
T _{RS}	Thermal reset of STATUS		135			°C
T _{HYST}	Thermal hysteresis (T _{TSD} -T _R)			7		°C
t _{SDL}	Status delay in overload conditions	T _j >T _{TSD} (see <i>Figure 4</i> .)			20	μs
V _{DEMAG}	Turn-off output voltage clamp	I _{OUT} =2A; V _{IN} =0; L=6mH	V _{CC} -41	V _{CC} -46	V _{CC} -52	٧
V _{ON}	Output voltage drop limitation	I _{OUT} =0.1A; T _j = -40°C+150°C (see <i>Figure 5</i> .)		25		mV

To ensure long term reliability under heavy overload or short circuit conditions, protection and related diagnostic signals must be used together with a proper software strategy. If the device is subjected to abnormal conditions, this software must limit the duration and number of activation cycles.

Table 9. Open load detection (8V<V_{CC}<18V)

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
I _{OL}	Openload ON state detection threshold	V _{IN} = 5V	10		70	mA
t _{DOL(on)}	Openload ON state detection delay	I _{OUT} = 0A, V _{CC} =13V (see <i>Figure 4.</i>)			200	μs
t _{POL}	Delay between INPUT falling edge and STATUS rising edge in openload condition	I _{OUT} = 0A (see <i>Figure 4</i> .)	200	500	1200	μs
V _{OL}	Openload OFF state voltage detection threshold	$V_{IN} = 0V$	2		4	>
t _{DSTKON}	Output short circuit to V_{CC} detection delay at turn Off	See Figure 4.	180		t _{POL}	μs
I _{L(off2)}	Off state output current	V _{IN} = 0V; V _{OUT} = 4V (see Section 3.4: Open load detection in Off state)	-75		0	μΑ
td_vol	Delay response from output rising edge to STATUS falling edge in open load	V _{IN} = 0V; V _{OUT} = 4V			20	μs

Table 10. Logic input

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{IL}	Input low level				0.9	V
I _{IL}	Low level input current	V _{IN} =0.9 V	1			μΑ
V _{IH}	Input high level		2.1			V
I _{IH}	High level input current	V _{IN} = 2.1 V			10	μΑ
V _{I(hyst)}	Input hysteresis voltage		0.25			V
V _{ICL}	Input clamp voltage	I _{IN} = 1mA I _{IN} = -1mA	5.5	-0.7	7	V V
V _{SDL}	STAT_DIS low level voltage				0.9	V
I _{SDL}	Low level STAT_DIS current	V _{SD} = 0.9 V	1			μΑ
V _{SDH}	STAT_DIS high level voltage		2.1			V
I _{SDH}	High level STAT_DIS current	V _{SD} = 2.1 V			10	μΑ
V _{SD(hyst)}	STAT_DIS hysteresis voltage		0.25			V
V _{SDCL}	STAT_DIS clamp voltage	I _{SD} = 1mA I _{SD} = -1mA	5.5	-0.7	7	V V

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Figure 4. Status timings

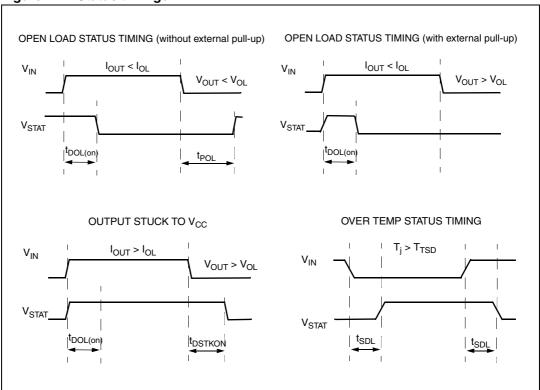
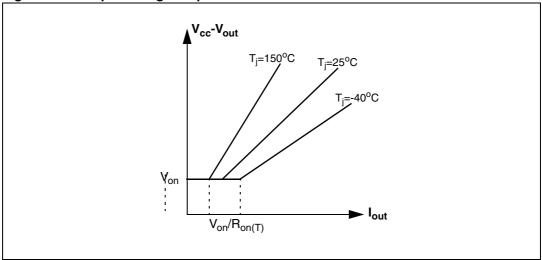


Figure 5. Output voltage drop limitation



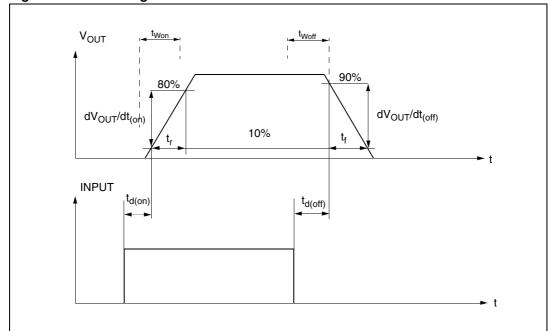


Figure 6. Switching characteristics

Table 11. Truth table

Conditions	INPUT	ОИТРИТ	STATUS (V _{SD} =0V) ⁽¹⁾
Normal Operation	L	L	Н
	Н	Н	Н
Overtemperature	L	L	Н
Overtemperature	Н	L	L
Undervoltage	L	L	X
Ondervoitage	Н	L	X
	Н	Х	Н
Overload &		(no power limitation)	
Short circuit to GND	Н	Cycling	L
		(power limitation)	
Output valtage - V	L	Н	L ⁽²⁾
Output voltage > V _{OL}	Н	Н	Н
Output aurrant . I	L	L	H ⁽³⁾
Output current < I _{OL}	Н	Н	L

- 1. If the $\rm V_{\rm SD}$ is high, the STATUS pin $\,$ is in a high impedance.
- 2. The STATUS pin is low with a delay equal to $\,\,t_{\mbox{DSTKON}}$ after INPUT falling edge.
- 3. The STATUS pin becomes high with a delay equal to $\,{\rm t_{POL}}$ after INPUT falling edge.

Table 12. Electrical transient requirements

ISO 7637-2:	Test levels ⁽¹⁾		Number of	Burst cycle/pulse		Delays and	
2004(E) Test pulse	III	IV	pulses or test times	repetition time		impedance	
1	-75 V	-100 V	5000 pulses	0.5 s	5 s	2 ms, 10 Ω	
2a	+37 V	+50 V	5000 pulses	0.2 s	5 s	50 μs, 2 Ω	
3a	-100 V	-150 V	1h	90 ms	100 ms	0.1 μs, 50 Ω	
3b	+75 V	+100 V	1h	90 ms	100 ms	0.1 μs, 50 Ω	
4	-6 V	-7 V	1 pulse			100 ms, 0.01 Ω	
5b ⁽²⁾	+65 V	+87 V	1 pulse			400 ms, 2 Ω	

ISO 7637-2: 2004(E)	Test level results ⁽¹⁾			
Test pulse	III	IV		
1	С	С		
2a	С	С		
3a	С	С		
3b	С	С		
4	С	С		
5b ⁽²⁾	С	С		

^{1.} The above test levels must be considered referred to Vcc = 13.5V except for pulse 5b.

^{2.} Valid in case of external load dump clamp: 40V maximum referred to ground.

Class	Contents	
С	All functions of the device are performed as designed after exposure to disturbance.	
Е	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.	

2.4 Waveforms



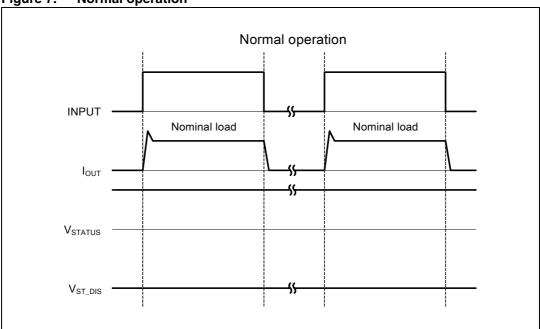
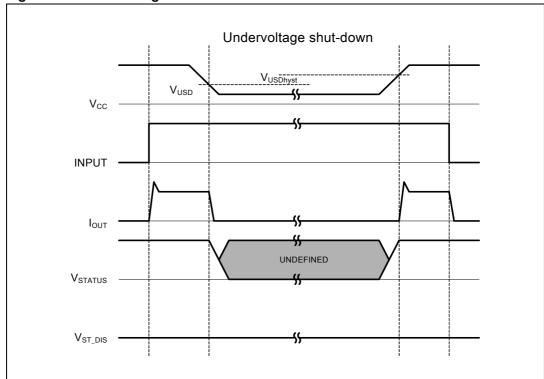


Figure 8. Undervoltage shutdown



Overload or Short to GND

INPUT

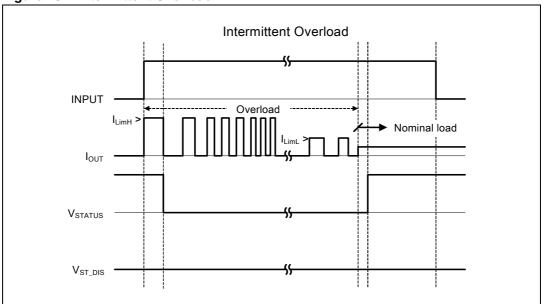
Power Limitation
Thermal cycling
ILimL

VSTATUS

VST_DIS

Figure 9. Overload or Short to GND





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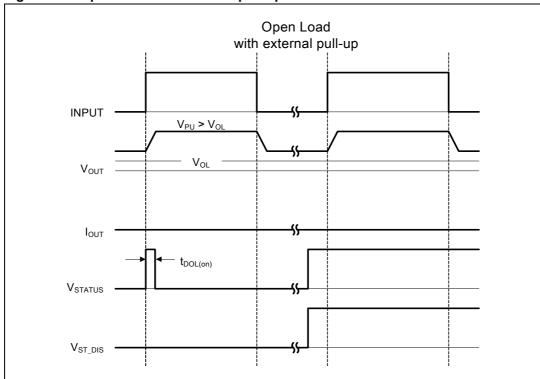
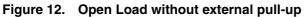


Figure 11. Open Load with external pull-up



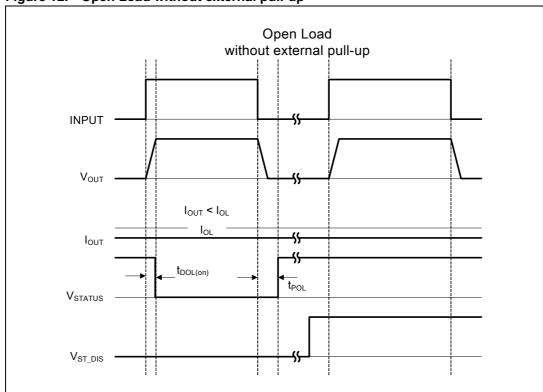


Figure 13. Short to V_{CC}

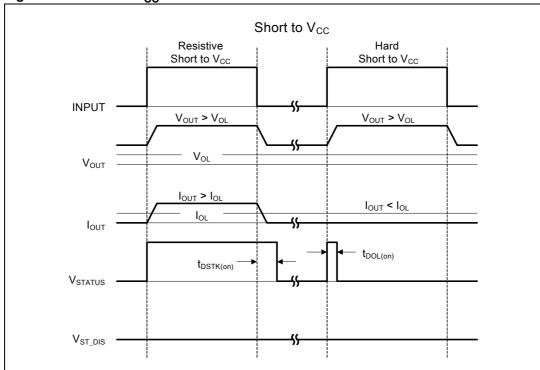
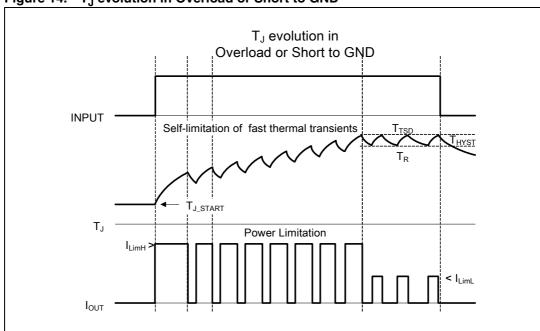


Figure 14. T_J evolution in Overload or Short to GND



2.5 Electrical characteristics curves

Figure 15. Off state output current

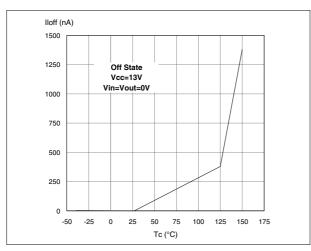


Figure 16. High level input current

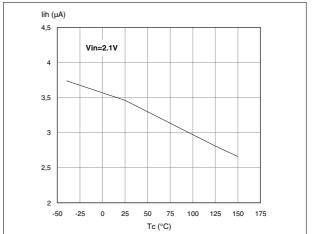


Figure 17. Input clamp voltage

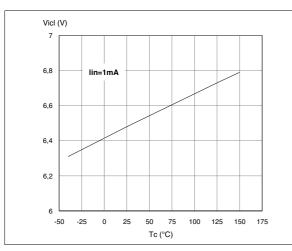


Figure 18. Input high level

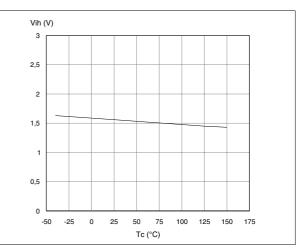


Figure 19. Input low level

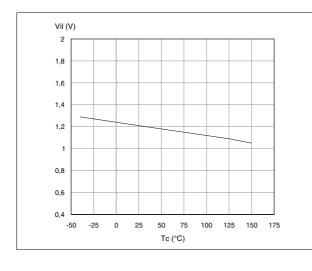


Figure 20. Low level STAT_DIS current

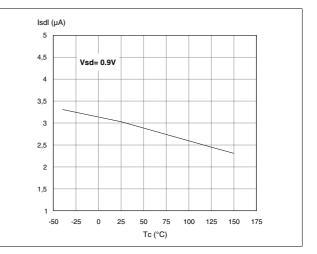


Figure 21. On state resistance vs T_{case}

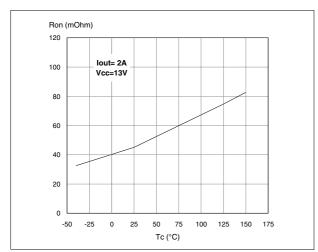


Figure 22. High level STAT_DIS current

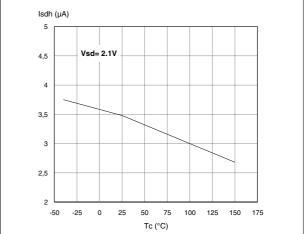


Figure 23. On state resistance vs V_{CC}

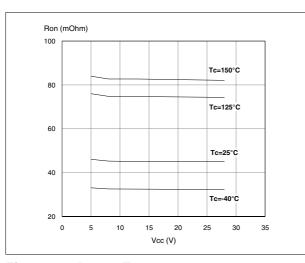


Figure 24. Low level input current

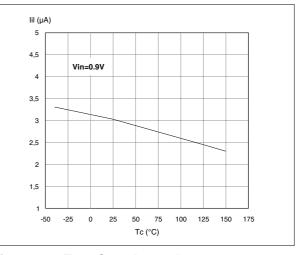


Figure 25. I_{LIM} vs T_{case}

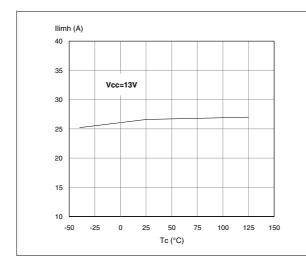


Figure 26. Turn-On voltage slope

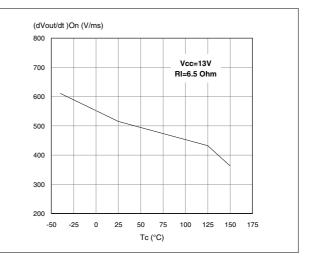
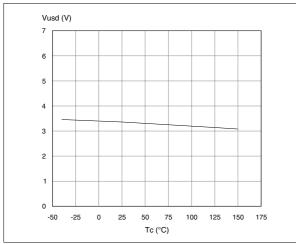


Figure 27. Undervoltage shutdown

Figure 28. Turn-Off voltage slope



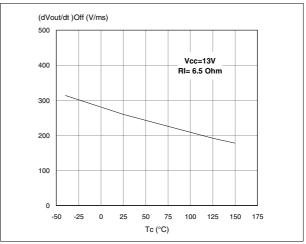
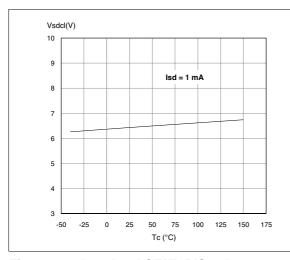


Figure 29. STAT_DIS clamp voltage

Figure 30. High level STAT_DIS voltage



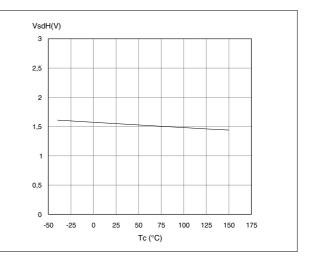
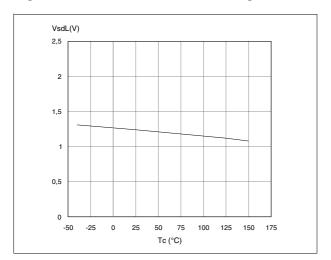
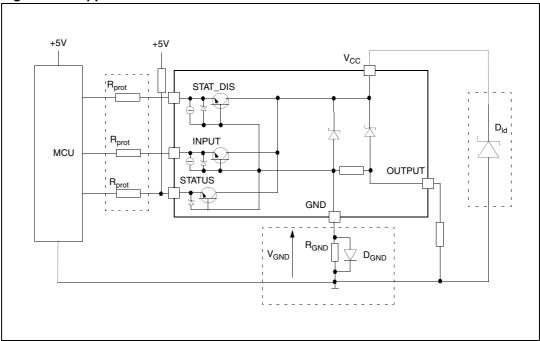


Figure 31. Low level STAT_DIS voltage



3 Application information

Figure 32. Application schematic



3.1 GND protection network against reverse battery

3.1.1 Solution 1: resistor in the ground line (R_{GND} only)

This solution can be used with any type of load.

The following is an indication on how to dimension the $\ensuremath{\mathsf{R}_{\mathsf{GND}}}$ resistor.

- 1. $R_{GND} \leq 600 \text{mV} / (I_{S(on)max})$.
- 2. $R_{GND} \ge (-V_{CC}) / (-I_{GND})$

where $-I_{GND}$ is the DC reverse ground pin current and can be found in the absolute maximum rating section of the device datasheet.

Power dissipation in R_{GND} (when V_{CC} <0: during reverse battery situations) is:

$$\mathsf{P}_\mathsf{D} = (-\mathsf{V}_\mathsf{CC})^2/\mathsf{R}_\mathsf{GND}$$

This resistor can be shared amongst several different HSDs. Please note that the value of this resistor should be calculated with formula (1) where $I_{S(on)max}$ becomes the sum of the maximum on-state currents of the different devices.

Please note that if the microprocessor ground is not shared by the device ground then the R_{GND} will produce a shift ($I_{S(on)max} * R_{GND}$) in the input thresholds and the status output values. This shift will vary depending on how many devices are ON in the case of several high side drivers sharing the same R_{GND} .

If the calculated power dissipation leads to a large resistor or several devices have to share the same resistor then ST suggests Solution 2 is used (see below).

3.1.2 Solution 2: diode (D_{GND}) in the ground line

A resistor (R_{GND} =1k Ω) should be inserted in parallel to D_{GND} if the device drives an inductive load.

This small signal diode can be safely shared amongst several different HSDs. Also in this case, the presence of the ground network will produce a shift (~600mV) in the input threshold and in the status output values, if the microprocessor ground is not common to the device ground. This shift will not vary if more than one HSD shares the same diode/resistor network.

3.2 Load dump protection

 D_{ld} is necessary (Voltage Transient Suppressor) if the load dump peak voltage exceeds to V_{CC} max DC rating. The same applies if the device is subject to transients on the V_{CC} line that are greater than the ones shown in the ISO T/R 7637/2 table.

3.3 MCU I/Os protection

If a ground protection network is used and negative transient are present on the V_{CC} line, the control pins will be pulled negative. ST suggests that a resistor (R_{prot}) be inserted in line to prevent the μC I/Os pins to latch-up.

The value of these resistors is a compromise between the leakage current of μC and the current required by the HSD I/Os (Input levels compatibility) with the latch-up limit of μC I/Os.

-V_{CCpeak}/I_{latchup} ≤R_{prot} ≤(V_{OHμC}-V_{IH}-V_{GND}) / I_{IHmax}

Calculation example:

For V_{CCpeak} = - 100V and $I_{latchup} \ge 20mA$; $V_{OH\mu C} \ge 4.5V$

 $5k\Omega \le R_{prot} \le 180k\Omega$

Recommended R_{prot} value is $10k\Omega$

3.4 Open load detection in Off state

Off-state open-load detection requires an external pull-up resistor (R_{PU}) connected between the OUTPUT pin and a positive supply voltage (V_{PU}) like the +5V line used to supply the microprocessor.

The external resistor has to be selected according to the following requirements:

- No false open load indication when load is connected: in this case we have to avoid V_{OUT} to be higher than V_{Olmin}; this results in the following condition V_{OUT}= (V_{PU}/(R_L+R_{PU}))R_L<V_{Olmin}.
- 2. No misdetection when load is disconnected: in this case the V_{OUT} has to be higher than V_{OLmax} ; this results in the following condition $R_{PU} < (V_{PU} V_{OLmax}) / I_{L(off2)}$.

Because $I_{s(OFF)}$ may significantly increase if V_{out} is pulled high (up to several mA), the pull-up resistor R_{PU} should be connected to a supply that is switched OFF when the module is in standby.

The values of V_{OLmin} , V_{OLmax} and $I_{L(off2)}$ are available in the Electrical characteristics section.

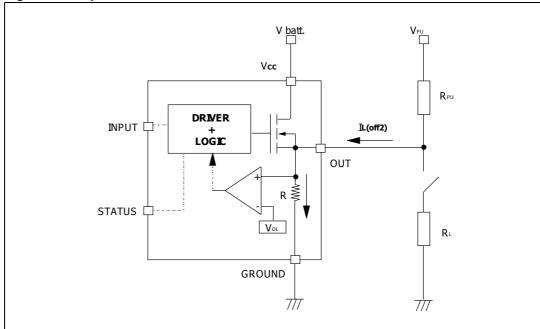
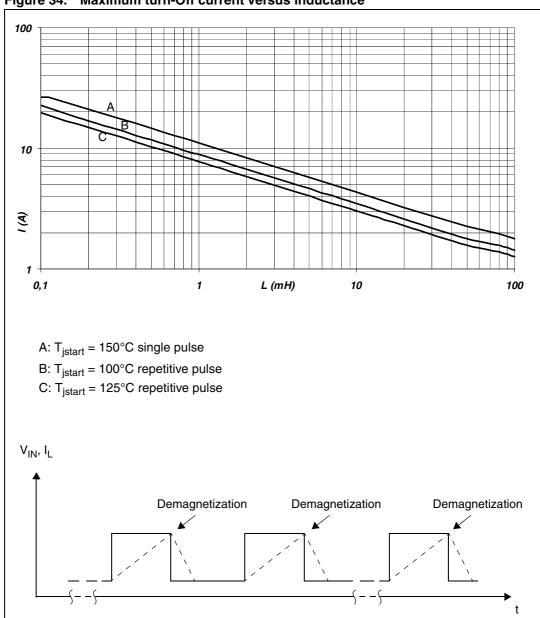


Figure 33. Open load detection in Off state

3.5 Maximum demagnetization energy ($V_{CC} = 13.5V$)

Figure 34. Maximum turn-Off current versus inductance



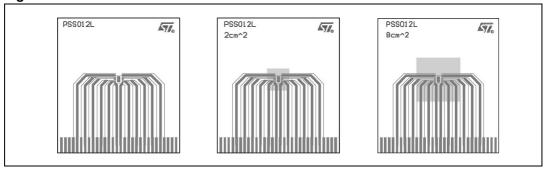
Note:

Values are generated with $R_L = 0 \Omega$ In case of repetitive pulses, T_{jstart} (at beginning of each demagnetization) of every pulse must not exceed the temperature specified above for curves A and B.

4 Package and PCB thermal data

4.1 PowerSSO-12 thermal data

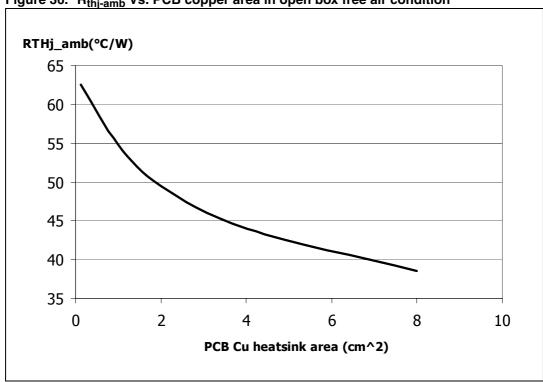
Figure 35. PowerSSO-12 PC board



Note: L

Layout condition of R_{th} and Z_{th} measurements (PCB: Double layer, Thermal Vias, FR4 area= 77mm x 86mm,PCB thickness=1.6mm, Cu thickness=70 μ m (front and back side), Copper areas: from minimum pad lay-out to 8cm²).

Figure 36. R_{thi-amb} Vs. PCB copper area in open box free air condition



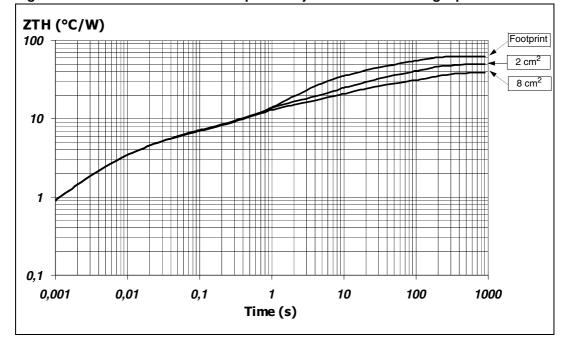
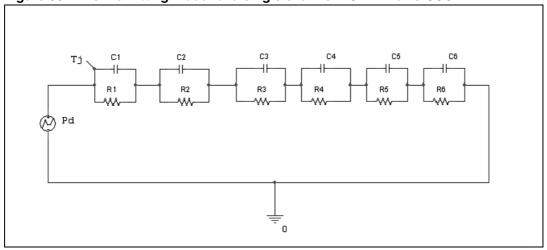


Figure 37. PowerSSO-12 thermal impedance junction ambient single pulse

Equation 1: pulse calculation formula

$$\begin{split} Z_{TH\delta} &= R_{TH} \cdot \ \delta + Z_{THtp} (1 - \delta) \\ \text{where } \delta &= t_P / T \end{split}$$

Figure 38. Thermal fitting model of a single channel HSD in PowerSSO-12 (a)



5/

a. The fitting model is a semplified thermal tool and is valid for transient evolutions where the embedded protections (power limitation or thermal cycling during thermal shutdown) are not triggered.

Table 13. Thermal parameter

Area/island (cm ²)	Footprint	2	8
R1 (°C/W)	0.7		
R2 (°C/W)	2.8		
R3 (°C/W)	3		
R4 (°C/W)	8	8	7
R5 (°C/W)	22	15	10
R6 (°C/W)	26	20	15
C1 (W.s/°C)	0.001		
C2 (W.s/°C)	0.0025		
C3 (W.s/°C)	0.0166		
C4 (W.s/°C)	0.2	0.1	0.1
C5 (W.s/°C)	0.27	0.8	1
C6 (W.s/°C)	3	6	9

Package and packing information 5

ECOPACK® packages 5.1

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second-level interconnect. The category of Second-Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97.

The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

5.2 Package mechanical data

Figure 39. PowerSSO-12 package dimensions

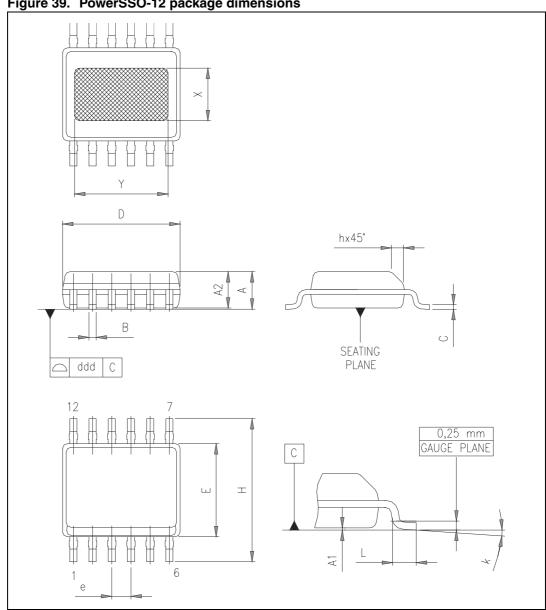


Table 14. PowerSSO-12 mechanical data

Symbol		Millimeters	
Symbol	Min.	Тур.	Max.
Α	1.250		1.620
A1	0.000		0.100
A2	1.100		1.650
В	0.230		0.410
С	0.190		0.250
D	4.800		5.000
E	3.800		4.000
е		0.800	
Н	5.800		6.200
h	0.250		0.500
L	0.400		1.270
k	0°		8°
Х	2.200		2.800
Y	2.900		3.500
ddd			0.100

5.3 Packing information

Figure 40. PowerSSO-12 tube shipment (no suffix)

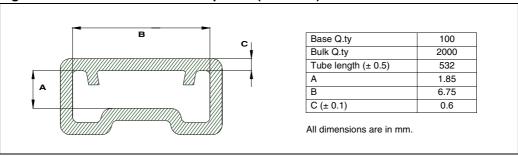
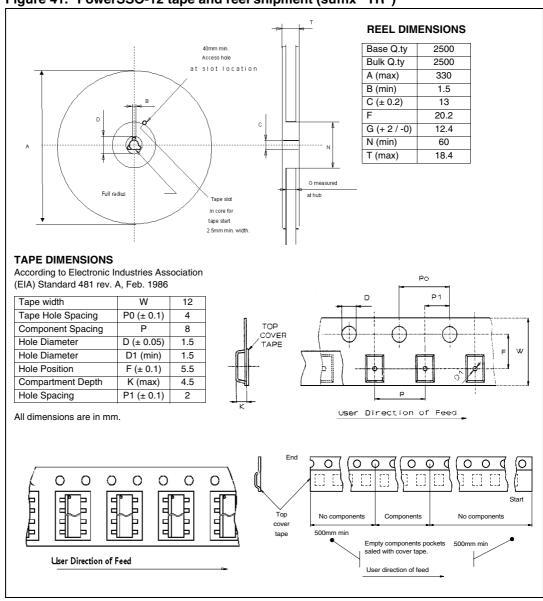


Figure 41. PowerSSO-12 tape and reel shipment (suffix "TR")



Order codes VN5E050J-E

6 Order codes

Table 15. Device summary

Pankago	Order codes		
Package	Tube	Tape and reel	
PowerSSO-12	VN5E050J-E	VN5E050JTR-E	

VN5E050J-E Revision history

7 Revision history

Table 16. Document revision history

Date	Revision	Changes
31-Aug-2007	1	Initial release.
19-Feb-2008	2	Document restructured. Changed <i>Description</i> on cover page. <i>Table 9: Open load detection (8V<v<sub>CC<18V)</v<sub></i> : added td_vol parameter. Changed <i>Section 2.4: Waveforms</i> . Added <i>Section 2.5: Electrical characteristics curves</i> . Added <i>Section 3.5: Maximum demagnetization energy (VCC = 13.5V)</i> . Added <i>Section 4.1: PowerSSO-12 thermal data</i> .

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